TOSHIBA LED Lamps

TLRE1100B(T11),TLSE1100B(T11),TLOE1100B(T11) TLYE1100B(T11),TLGE1100B(T11),TLFGE1100B(T11) TLPGE1100B(T11)

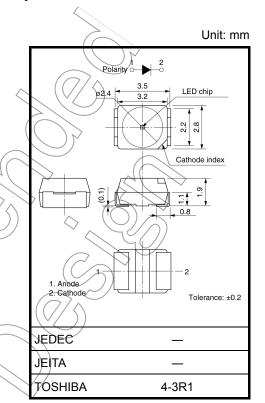
Panel Circuit Indicators

- Surface-mount devices
- 3.2 (L) mm × 2.8 (W) mm × 1.9 (H) mm
- Flat-top type
- InGaAlP LEDs
- · High luminous intensity
- Low drive current, high-intensity light emission
- Colors: red, orange, yellow, green, pure green
- Applications: automotive use, message signboards, backlighting, etc.
- Standard embossed tape packing: T11 (2000 pcs / reel)

8-mm tape reel

Color and Material

Part Number	Color	Material
TLRE1100B	Red	
TLSE1100B	Red	
TLOE1100B	Orange	$\langle C \rangle$
TLYE1100B	Yellow	InGaAlP
TLGE1100B	Green	
TLFGE1100B	Green	
TLPGE1100B	Pure Green	
$\langle \rangle$	7	



Weight: 0.035 g (typ.)



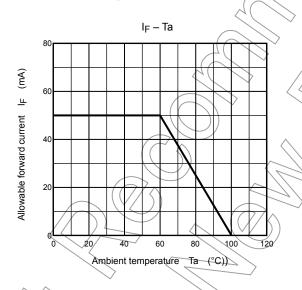
Absolute Maximum Ratings (Ta = 25°C)

Part Number	Forward Current I _F (mA) See Note 1	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operation Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLRE1100B					
TLSE1100B				^	
TLOE1100B					
TLYE1100B	50	4	120	-40 to 100	-40 to 100
TLGE1100B					~
TLFGE1100B			^	(7/1)	
TLPGE1100B					

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Forward current derating



Electrical Characteristics (Ta = 25°C)

			(/ / /			
Part Number		Forward V	/oftage V _F			Current
	Min	\	Max	/ I _F	Max	V_{R}
TLRE1100B	1.6	1,9	2.4			
TLSE1100B	1.6	1.9	2.4			
TLOE1100B	1.6	2.0	2.4			
TLYE1100B	1.6	2.0	2.4	20	10	4
TLGE1100B	1.6	2.0	2.4			
TLFGE1100B	1.6	2.0	2.4			
TLPGE1100B	1.6	2.1	2.4			
Unit		V		mA	μА	٧



Optical Characteristics-1 (Ta = 25°C)

Part Number	Luminous Intensity I _V			Available Iv rank	
Fait Number	Min	Тур.	Max	lF	Please see Note 2
TLRE1100B	40	100	320	20	PA/QA/RA/SA
TLSE1100B	63	180	500	20	QA/RA/SA/TA
TLOE1100B	63	150	500	20	QA/RA/SA/TA
TLYE1100B	63	150	500	20	QA/RA/SA/TA
TLGE1100B	40	100	320	20	PA/QA/RA/SA
TLFGE1100B	25	45	125	20	NA / PA / QA
TLPGE1100B	10	25	50	20	LA / MA / NA
Unit	mcd	mcd	mcd	mA	

Note 2: The specification on the above table is used for Iv classification of LEDs in Toshiba facility.

Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

Rank	Luminous Intensity IV			
Naik	Min	Max		
LA	10	20		
MA	16	32		
NA	25	50		
PA	40	80		
QA	63	125		
RA	100	200		
SA	160	320		
TA	250	500		
Unit	mcd	mca		

Optical Characteristics-2 (Ta = 25°C)

	/_/)]	\smile			/ { \		
		//_		Emission	Spectrum			
Part Number	_	ak Emiss evelength	- /	Δλ	Domina	nt Wavele	ength λ _d	Ιϝ
\sim	∕∑Min	Typ.	Max	Typ.	Min	Тур.	Max	-1
TLRE1100B	D	644	-	18	624	630	638	
TLSE1100B)	623	$\prec 1$	15	607	613	621	
TLOE1100B)}	612		15	599	605	613	
TLYE1100B	_	590	(-)	15	581	587	595	20
TLGE1100B		574)	13	565	571	576	
TLFGE1100B	_	568	\nearrow	11	561	565	569	
TLPGE1100B	_	562	_	11	555	558	564	
Unit		nm		nm		nm		mA

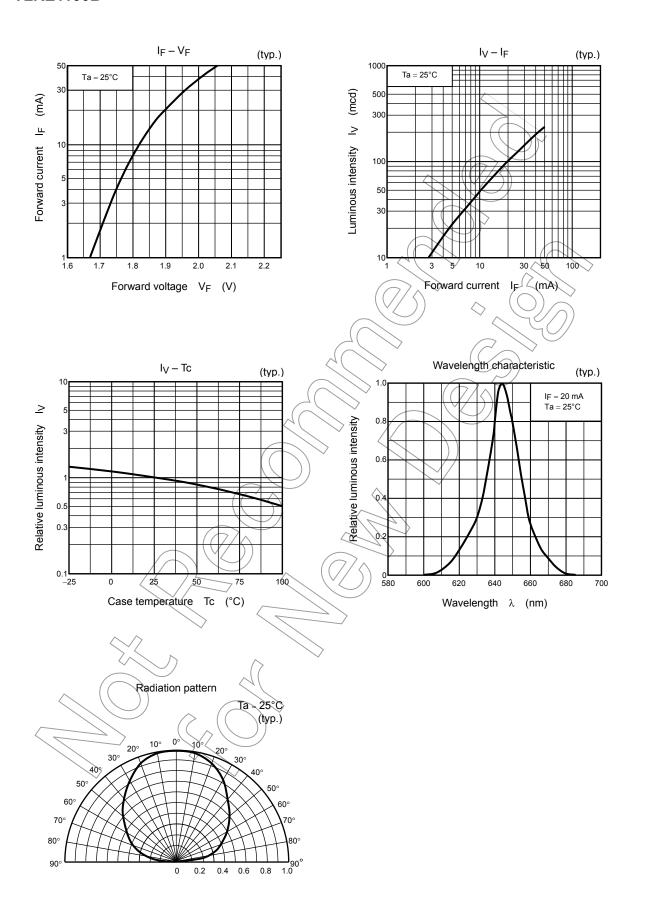
The cautions

- This visible LED lamp also emits some IR light.

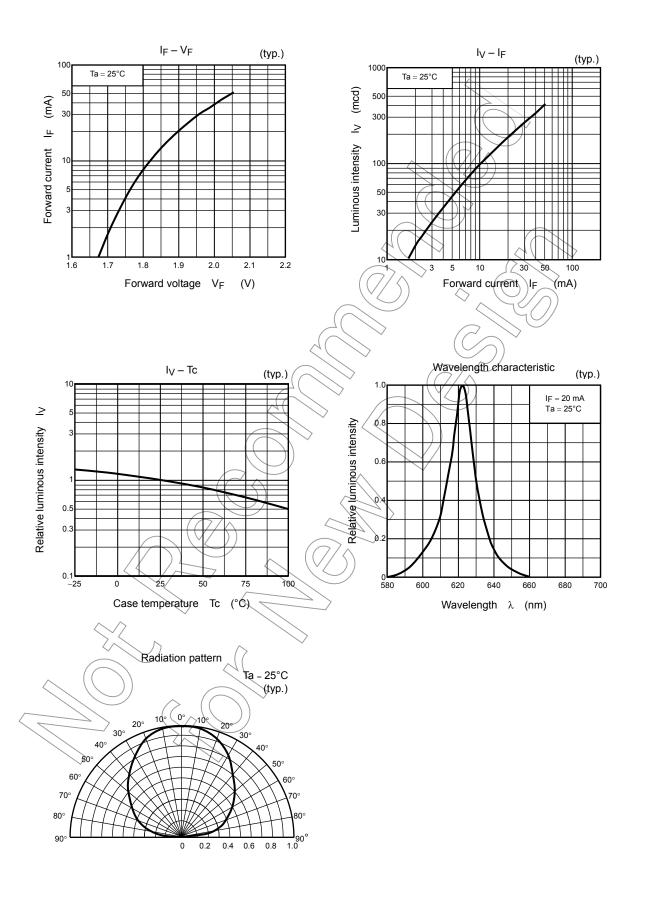
 If a photodetector is located near the LED lamp, please ensure that it will not be affected by the IR light.
- This product is designed as a general display light source usage, and it has applied the measurement standard that matched with the sensitivity of human's eyes. Therefore, it is not intended for usage of functional application (ex. Light source for sensor, optical communication and etc) except general display light source.

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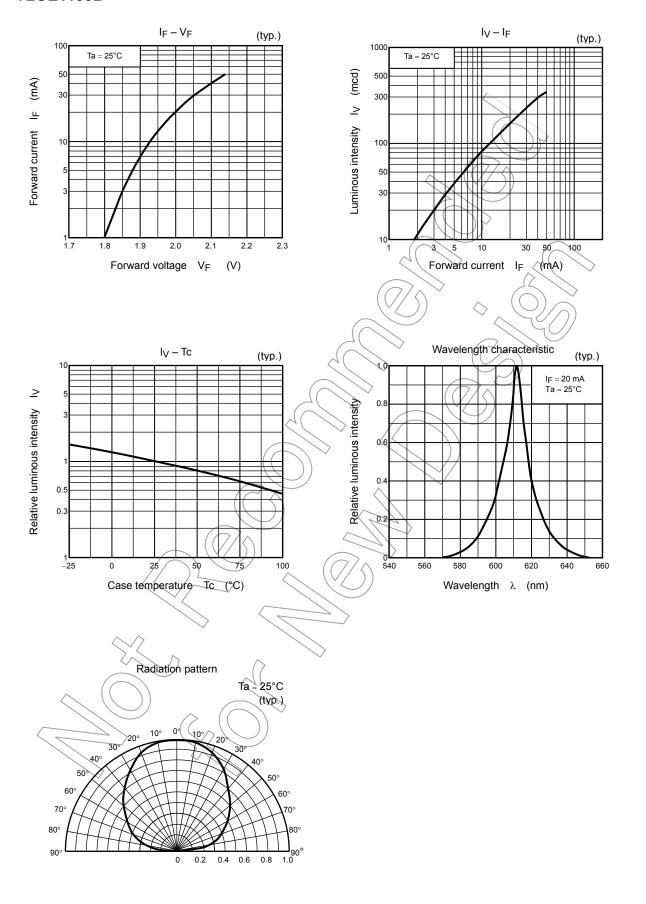
TLRE1100B



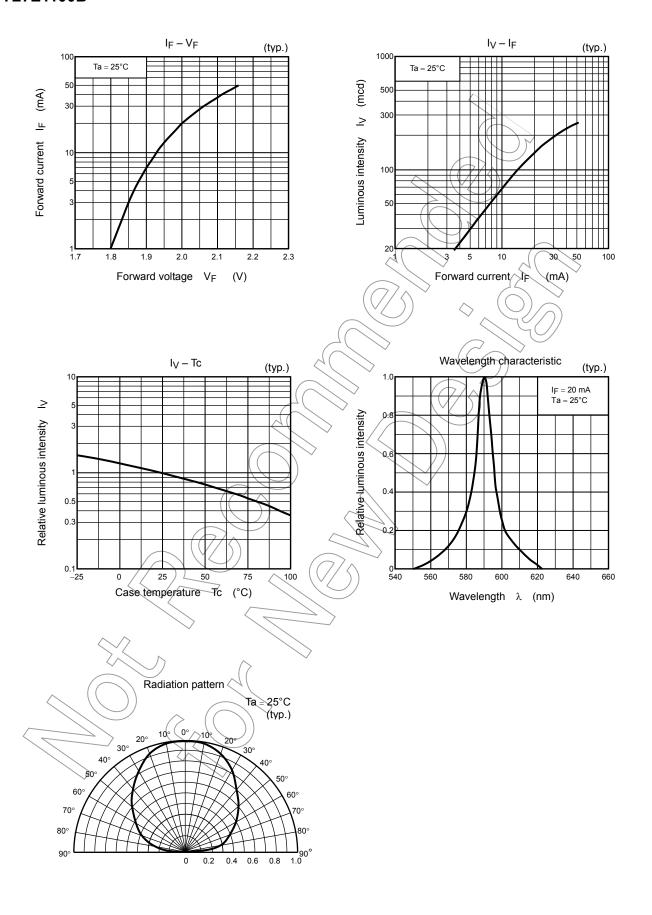
TLSE1100B



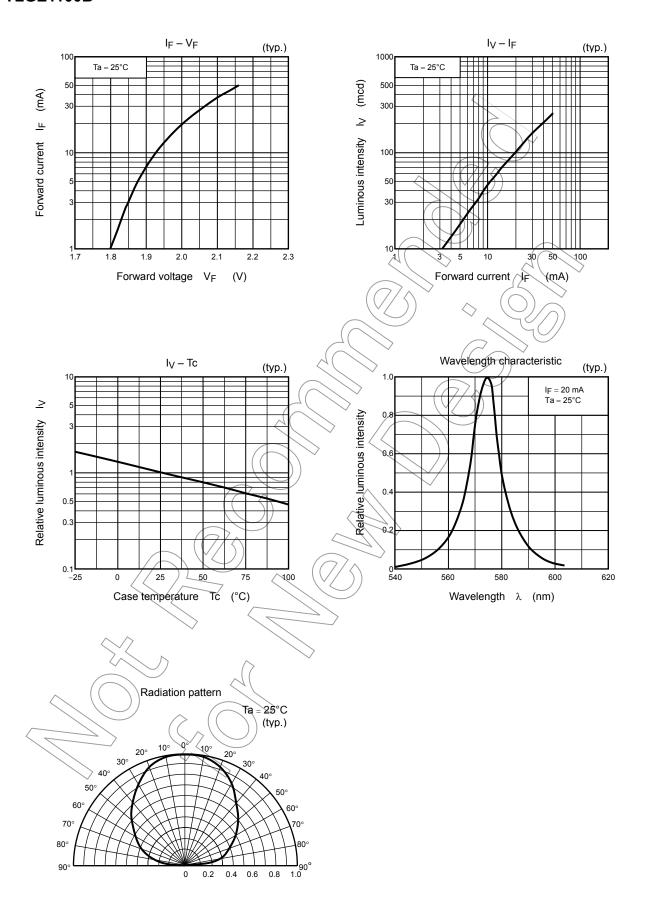
TLOE1100B



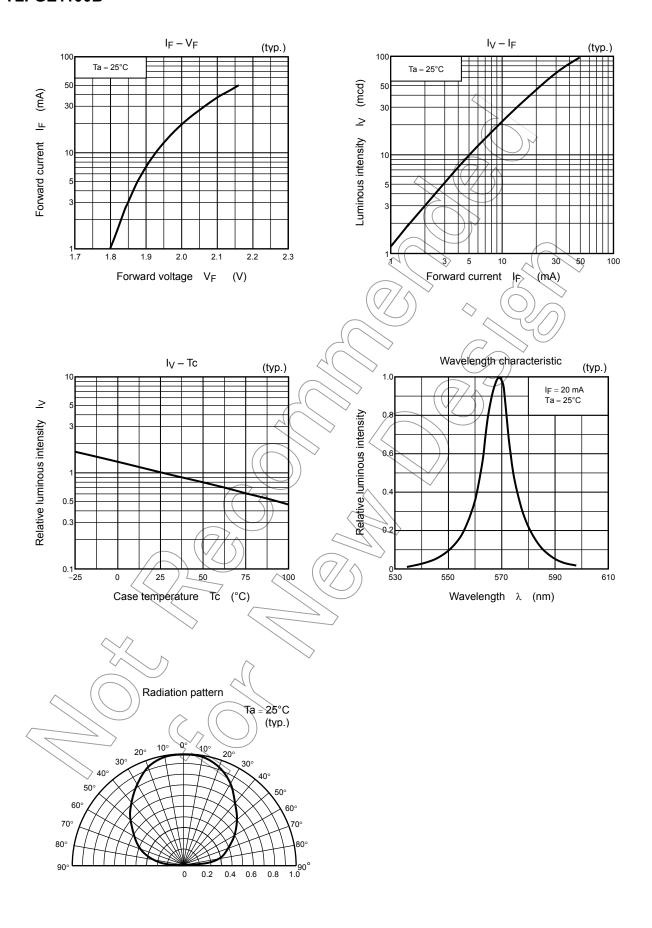
TLYE1100B



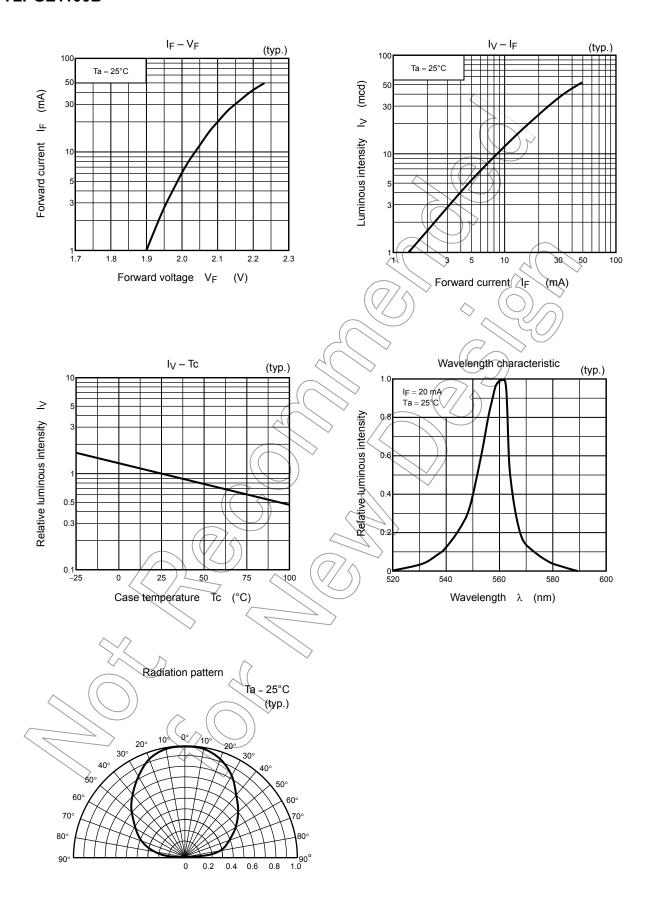
TLGE1100B



TLFGE1100B



TLPGE1100B



Packaging

These LED devices are packed in an aluminum envelope with a silica gel and a moisture indicator to avoid moisture absorption. The optical characteristics of the devices may be affected by exposure to moisture in the air before soldering and they should therefore be stored under the following conditions:

1. This moisture proof bag may be stored unopened within 12 months at the following conditions. Temperature: 5°C to 30°C

Humidity: 90% (max)

- 2. After opening the moisture proof bag, the devices should be assembled within 168 hours in an environment of 5°C to 30°C/60% RH or below.
- 3. If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the devices should be baked in taping with reel. After baking, use the baked devices within 72 hours, but perform baking only once. Baking conditions: 60±5°C, for 12 to 24 hours.
 - Expiration date: 12 months from sealing date, which is imprinted on the same side as this label affixed.
- 4. Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting. Furthermore, prevent the devices from being destructed against static electricity for baking of it.
- 5. If the packing material of laminate would be broken, the hermeticity would deteriorate. Therefore do not throw or drop the packed devices.

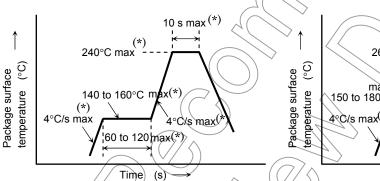
Mounting Method

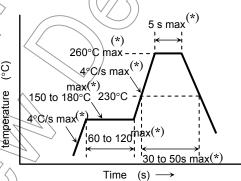
Soldering

• Reflow soldering (example)

Temperature profile for Pb soldering (example)

Temperature profile for Pb-free soldering (example)





- The products are evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 168 h of opening the package.
- Second reflow soldering

In case of second reflow soldering should be performed within 168 h of the first reflow under the above conditions

Storage conditions before the second reflow soldering: 30°C, 60% RH (max)

Make any necessary soldering corrections manually.

(only once at each soldering point)

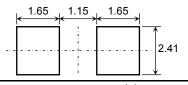
Soldering iron: 25 W Temperature: 300°C or less

Temperature: 300°C or less
Time: within 3 s

• If the products need to be performed by other soldering method (ex. wave soldering), please contact Toshiba sales representative.



Unit: mm



Cleaning

When cleaning is required after soldering, Toshiba recommends the following cleaning solvents. It is confirmed that these solvents have no effect on semiconductor devices in our dipping test (under the recommended conditions). In selecting the one for your actual usage, please perform sufficient review on washing condition, using condition and etc.

ASAHI CLEAN AK-225AES: (made by ASAHI GLASS)

KAO CLEAN THROUGH 750H: (made by KAO)

PINE ALPHA ST-100S: (made by ARAKAWA CHEMICAI

Precautions when Mounting

Do not apply force to the plastic part of the LED under high-temperature conditions.

To avoid damaging the LED plastic, do not apply friction using a hard material.

When installing the PCB in a product, ensure that the device does not come into contact with other emponents.

Tape Specifications

1. Product number format

The type of package used for shipment is denoted by a symbol suffix after the product number. The method of classification is as below. (this method, however does not apply to products whose electrical characteristics differ from standard Toshiba specifications)

- (1) Tape Type: T14 (4-mm pitch)
- (2) Example

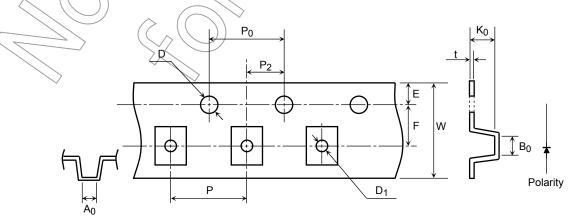
TLRE1100B (T11)
Tape type
Toshiba product No.

2. Tape dimensions

Unit: mm

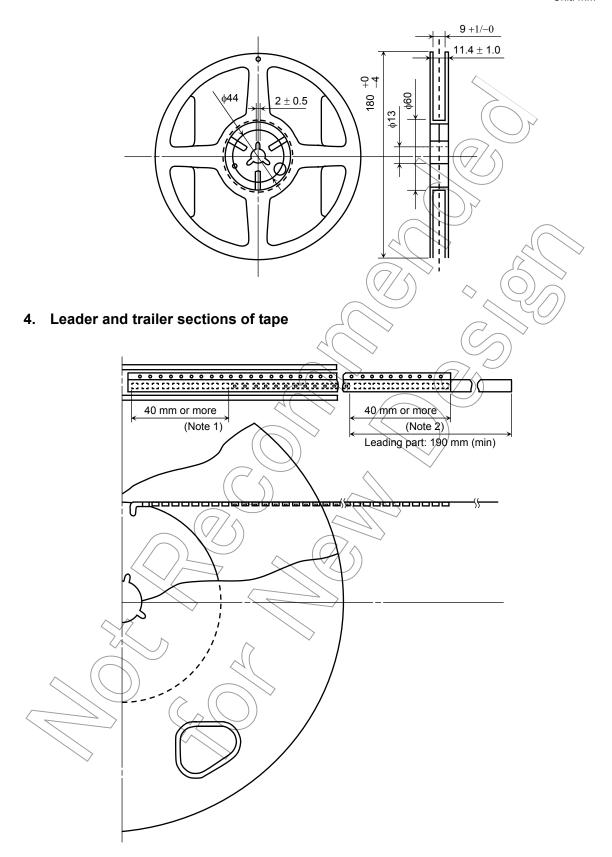
Symbol	Dimension	Tolerance
D	//1.5)	+0.1/-0
Е	1.75	±0.1
P ₀	4.0	±0.1
t 🚫	→ 0.3	±0.05
F 🗸	3,5	±0.05
D ₁	1.5	±0.1

Symbol	Dimension	Tolerance
(P ₂ / /)	2.0	±0.05
M	8.0	±0.3
P	4.0	±0.1
A ₀	2.9	±0.1
→ B ₀	3.7	±0.1
K ₀	2.3	±0.1



3. Reel dimensions

Unit: mm



Note 1: Empty trailer section

Note 2: Empty leader section



5. Packing form

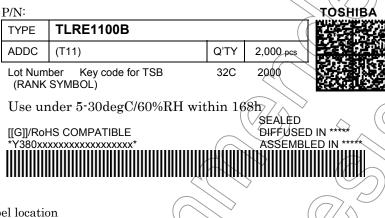
(1) Packing quantity

Reel	2,000 pcs
Carton	10,000 pcs

(2) Packing form: Each reel is sealed in an aluminum pack with silica gel.

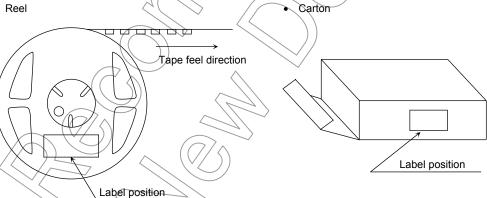
6. Label format

(1) Example: TLRE1100B (T11)



(2) Label location

Reel



The aluminum package in which the reel is supplied also has the label attached to center of one side.

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